

L Number	Hits	Search Text	DB	Time stamp
-	107	microstructure and (3-D "three-dimensional" "three dimensional" "three dimension" "three dimentions") and (deform deforming deformable deformed)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/03 08:58
-	50	microstructure and (3-D "three-dimensional" "three dimensional" "three dimension" "three dimentions") and (deform deforming deformable deformed) and (predetermined predetermin predetermining)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/03 08:59
-	50	microstructure and (3-D "three-dimensional" "three dimensional" "three dimension" "three dimentions") and (deform deforming deformable deformed) and (predetermined predetermin predetermining) and (portion part section sectional)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/03 09:00
-	5	microstructure and (3-D "three-dimensional" "three dimensional" "three dimension" "three dimentions") and (deform deforming deformable deformed) and (predetermined predetermin predetermining) and (portion part section sectional) and (direction directional directioning way) and angle and @ad < "19990618"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/03 09:02
-	29	microstructure and (3-D "three-dimensional" "three dimensional" "three dimension" "three dimentions") and (deform deforming deformable deformed) and (predetermined predetermin predetermining) and (portion part section sectional) and (direction directional directioning way) and angle	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/03 10:24
-	1719	(deform deformed deformation deforming spoiled spoiling spoil) and (structure microstructure construction) and (3-D "3 dimention" "three dimension" "3-dimension" "3_dimension" "three-dimension" "three dimension:")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/09 15:58
-	1719	(deform deformed deformation deforming spoiled spoiling spoil) and (structure microstructure construction) and (3-D "3 dimention" "three dimension" "3-dimension" "3_dimension" "three-dimension" "three dimension")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/09 15:58
-	1910	(deform deformed deformation deforming spoiled deformable spoiling spoil) and (structure microstructure construction) and (3-D "3 dimention" "three dimension" "3-dimension" "3_dimension" "three-dimension" "three dimension")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/09 16:02
-	1910	(deform deformed deformation deforming spoiled deformable spoiling spoil) and (structure microstructure construction) and (3-D "3 dimention" "three dimension" "3-dimension" "3_dimension" "three-dimension" "three dimension")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/09 16:08
-	1571	(deform deformed deformation deforming spoiled deformable spoiling spoil) and (structure microstructure construction) and (3-D "3 dimention" "three dimension" "3-dimension" "3_dimension" "three-dimension" "three dimension") and (portion portional portionaly)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/09 16:08
-	1858	(deform deformed deformation deforming spoiled deformable spoiling spoil) and (structure microstructure construction) and (3-D "3 dimention" "three dimension" "3-dimension" "3_dimension" "three-dimension" "three dimension") and (portion part parts partial partially portional portionaly)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/09 16:09
-	1006	(deform deformed deformation deforming spoiled deformable spoiling spoil) and (structure microstructure construction) and (3-D "3 dimention" "three dimension" "3-dimension" "3_dimension" "three-dimension" "three dimension") and (predetermined predetermining predetermin predetermination preset setted)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/09 16:14

-	1896	(deform deformed deformation deforming spoiled deformable spoiling spoil) and (structure microstructure construction) and (3-D "3 dimentiiion" "three dimention" "3-dimension" "3_dimention" "three-dimension" "three dimention") and (predetermined predetermining predetermin predetermination preset setted) and electroplating	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/09 16:14
-	1299	(deform deformed deformation deforming spoiled deformable spoiling spoil) and (structure microstructure construction) and (3-D "3 dimentiiion" "three dimention" "3-dimension" "3_dimention" "three-dimension" "three dimention") and (predetermined predetermining predetermin predetermination preset setted) and title	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/09 16:23
-	342	thickness and (coating electroplating) and ((deform deformed deformation deforming spoiled deformable spoiling spoil) and (structure microstructure construction) and (3-D "3 dimentiiion" "three dimention" "3-dimension" "3_dimention" "three-dimension" "three dimention") and (predetermined predetermining predetermin predetermination preset setted) and title)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/09 16:18
-	97	(thickness and (coating electroplating) and ((deform deformed deformation deforming spoiled deformable spoiling spoil) and (structure microstructure construction) and (3-D "3 dimentiiion" "three dimention" "3-dimension" "3_dimention" "three-dimension" "three dimention") and (predetermined predetermining predetermin predetermination preset setted) and title)) and (portion portionally portional part parts partial partially) and (positioning placing place placement position positioned placed) and (adjacent near close adjoining joined) and @ad < "20000614"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/09 16:49
-	67	(thickness and (coating electroplating) and ((deform deformed deformation deforming spoiled deformable spoiling spoil) and (structure microstructure construction) and (3-D "3 dimentiiion" "three dimention" "3-dimension" "3_dimention" "three-dimension" "three dimention") and (predetermined predetermining predetermin predetermination preset setted) and title)) and (portion portionally portional part parts partial partially) and (positioning placing place placement position positioned placed) and (adjacent near close adjoining joined) and @ad < "20000614"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/09 16:33
-	0	and (deforming deformed deform spoil spoiling) (thickness and (coating electroplating) and ((deform deformed deformation deforming spoiled deformable spoiling spoil) and (structure microstructure construction) and (3-D "3 dimentiiion" "three dimention" "3-dimension" "3_dimention" "three-dimension" "three dimention") and (predetermined predetermining predetermin predetermination preset setted) and title)) and (portion portionally portional part parts partial partially) and (positioning placing place placement position positioned placed) and (adjacent near close adjoining joined) and @ad < "20000614"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/09 16:30
-	56	and (deforming deformed deform spoil spoiling) and tetrahedra (thickness and (coating electroplating) and ((deform deformed deformation deforming spoiled deformable spoiling spoil) and (structure microstructure construction) and (3-D "3 dimentiiion" "three dimention" "3-dimension" "3_dimention" "three-dimension" "three dimention") and (predetermined predetermining predetermin predetermination preset setted) and title)) and (portion portionally portional part parts partial partially) and (positioning placing place placement position positioned placed) and (adjacent near close adjoining joined) and @ad < "20000614"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/09 16:32
		and (deforming deformed deform spoil spoiling) and square		

-	7	(thickness and (coating electroplating) and ((deform deformed deformation deforming spoiled deformable spoiling spoil) and (structure microstructure construction) and (3-D "3 dimention" "three dimention" "3-dimension" "3_dimension" "three-dimension" "three dimention")) and (predetermined predetermining predetermin predetermination preset setted) and title)) and (portion portionally portional part parts partial partially) and (positioning placing place placement position positioned placed) and (adjacent near close adjoining joined) and @ad < "20000614" and (deforming deformed deform spoil spoiling bend bending bended) and Lithographic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/09 16:34
-	75	(thickness and (coating electroplating) and ((deform deformed deformation deforming spoiled deformable spoiling spoil) and (structure microstructure construction) and (3-D "3 dimention" "three dimention" "3-dimension" "3_dimension" "three-dimension" "three dimention")) and (predetermined predetermining predetermin predetermination preset setted) and title)) and (portion portionally portional part parts partial partially) and (positioning placing place placement position positioned placed) and (adjacent near close adjoining joined) and @ad < "20000614" and (deforming deformed deform spoil spoiling bend bending bended)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/09 16:44
-	2	(electroplate electroplating) and (structure microstructure) and @ad < "20000614" and thickness and (dimention dimentional) and (bending bended bend spoil spoiled deform deforming deformed)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/09 16:52
-	2905	(electroplate electroplating) and (structure microstructure) and @ad < "20000614" and (bending bend bended spoiled spoiling spoil deform deforming deformed)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/09 17:39
-	2	(electroplate electroplating) and (structure microstructure) and @ad < "20000614" and (bending bend bended spoiled spoiling spoil deform deforming deformed) and dimention	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/09 17:43
-	2	(electroplate electroplating) and (structure microstructure) and @ad < "20000614" and (bending bend bended spoiled spoiling spoil deform deforming deformed) and dimention	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/09 17:42
-	1227	(electroplate electroplating) and (structure microstructure) and @ad < "20000614" and (bending bend bended spoiled spoiling spoil deform deforming deformed) and (predetermined preset)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/09 17:44
-	883	(electroplate electroplating) and (structure microstructure) and @ad < "20000614" and (bending bend bended spoiled spoiling spoil deform deforming deformed) and (predetermined preset) and adjacent	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/09 17:48
-	100	(electroplate electroplating) and (structure microstructure) and @ad < "20000614" and (bending bend bended spoiled spoiling spoil deform deforming deformed) and (predetermined preset) and (MEMS "microelectromechanical system")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/09 17:59
-	1	(electroplate electroplating) and (structure microstructure) and @ad < "20000614" and (bending bend bended spoiled spoiling spoil deform deforming deformed) and (predetermined preset) and (MEMS "microelectromechanical system") and (3-D "3 dimention" "three dimention" "3-dimension" "3_dimension" "three-dimension" "three dimention" "three dimention"))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/09 17:52

-	101	(electroplate electroplating) and (structure microstructure) and @ad < "20000614" and (bending bend bended spoiled spoiling spoil deform deforming deformed deformation deformable) and (predetermined preset) and (MEMS "microelectromechanical system") and (dimention photolithographic polymer metal microelectronics prototype lithographic fiber coat portion pattern patterning)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/09 18:07
-	40	(electroplate electroplating) and (structure microstructure) and @ad < "20000614" and (bending bend bended spoiled spoiling spoil deform deforming deformed deformation deformable) and (predetermined preset) and (MEMS "microelectromechanical system") and (dimention photolithographic polymer metal microelectronics prototype lithographic fiber coat portion pattern patterning) not printer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/09 18:08
-	34	(electroplate electroplating) and (structure microstructure) and @ad < "20000614" and (bending bend bended spoiled spoiling spoil deform deforming deformed deformation deformable) and (predetermined preset) and (MEMS "microelectromechanical system") and (dimention photolithographic polymer metal microelectronics prototype lithographic fiber coat portion pattern patterning) not printer not medical	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/09 18:50
-	102	(electroplate electroplating) and (structure microstructure) and @ad < "20000614" and (bending bend bended spoiled spoiling spoil deform deforming deformed deformation deformable) and (predetermined preset) and (MEMS "microelectromechanical system") and structure	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/09 19:05
-	1681492	WO 96/29629	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/09 19:15
-	3	WO96/29629	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/10 10:40
-	542	Jackman.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/10 10:40
-	20	Jackman.in. and rebecca	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/10 10:54
-	205	deform\$ adj2 (structure microstructure) adj4 (portion partial partially part portional portionally)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/10 10:56
-	0	deform\$ adj2 (structure microstructure) adj4 (portion partial partially part portional portionally) and (dimention dimentional)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/10 10:57
-	155	deform\$ adj2 (structure microstructure) adj4 (portion partial partially part portional portionally) and @ad < "20000615"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/10 10:59

-	102	deform\$ adj2 (structure microstructure) adj4 (portion partial partially part portional portionally) and @ad < "20000615" not (flow fluid water liquit)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/10 11:02
-	42	bend\$ adj2 (structure microstructure) adj4 (portion partial partially part portional portionally) and @ad < "20000615" not (flow fluid water liquit)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/10 11:13
-	1671	semiconductor and package and lead and bending and deform\$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/10 11:14
-	0	semiconductor and package and lead and bending and deform\$ and dimention\$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/10 11:14
-	346	semiconductor and package and lead and bending and deform\$ and (3D 2D 3-D 2-D)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/10 11:16
-	888	semiconductor and package and lead and bending and deform\$ and (3D 2D 3-D 2-D) jackman.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/10 11:15
-	0	semiconductor and package and lead and bending and deform\$ and (3D 2D 3-D 2-D) and jackman.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/10 11:15
-	323	semiconductor and package and lead and bending and deform\$ and (3D 2D 3-D 2-D) and (structure microstructure)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/10 11:17
-	225	semiconductor and package and lead and bending and deform\$ and (3D 2D 3-D 2-D) and (structure microstructure) and predetermin\$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/10 11:18
-	11	semiconductor and package and lead and bending and deform\$ and (3D 2D 3-D 2-D) and (structure microstructure) and "zig-zag"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/10 11:20
-	21804	"zig-zag"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/10 11:20
-	1206	"zig-zag" and deform\$ and bend\$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/10 11:22

-	1	"zig-zag" and deform\$ and bend\$ and dimention\$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/10 16:17
-	0	"discontinuous pattern" and mountain	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/10 16:17
-	20	"discontinuous pattern" and mountain	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/10 16:20
-	0	"discontinuous pattern" and mountain and jackman.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/10 16:18
-	13	"discontinuous pattern" and mountain and structure	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/10 16:18
-	13	"discontinuous pattern" and mountain and (structure microstructure)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/10 16:19
-	38673	"discontinuous pattern" and mountain and (structure microstructure) "dash line"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/10 16:19
-	0	"discontinuous pattern" and mountain and (structure microstructure) and "dash line"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/10 16:19
-	1	"discontinuous pattern" and mountain and (structure microstructure) and "2-D"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/10 16:20
-	0	"discontinuous pattern" and mountain adj fold and (structure microstructure) and "2-D"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/10 16:20
-	0	"discontinuous pattern" and mountain adj fold	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/10 16:21
-	128	mountain adj fold	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/10 16:21

-	8	mountain adj fold and discontinuous	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/10 16:21
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